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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	384
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	896-BBGA, FCBGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxmb3g4f31c5n

Symbol	Description	Condition	Minimum ⁽¹⁾	Typical	Maximum ⁽¹⁾	Unit
V _{CCIO}	I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V	1.283	1.35	1.418	V
		1.25 V	1.19	1.25	1.31	V
		1.2 V	1.14	1.2	1.26	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply	—	1.425	1.5	1.575	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V _I	DC input voltage	—	−0.5	—	3.6	V
V _O	Output voltage	—	0	—	V _{CCIO}	V
T _J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	−40	—	100	°C
t _{RAMP} ⁽⁴⁾	Power supply ramp time	Standard POR	200 μs	—	100 ms	—
		Fast POR	200 μs	—	4 ms	—

⁽¹⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁴⁾ This is also applicable to HPS power supply. For HPS power supply, refer to t_{RAMP} specifications for standard POR when HPS_PORSEL = 0 and t_{RAMP} specifications for fast POR when HPS_PORSEL = 1.

Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCL_GXBR}	GX and SX speed grades—clock network power (right side)				
V _{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	1.17	1.20	1.23	V
V _{CCL_GXBR}	GT and ST speed grades—clock network power (right side)				

Related Information**Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines**

Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions**Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices**

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
V _{CC_HPS}	HPS core voltage and periphery circuitry power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	⁽¹⁵⁾	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5 \times V_{CCIO}$	—	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.44	0.44

Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Transmitter REFCLK phase noise ⁽⁴³⁾	10 Hz	—	—	–50	dBc/Hz
	100 Hz	—	—	–80	dBc/Hz
	1 KHz	—	—	–110	dBc/Hz
	10 KHz	—	—	–120	dBc/Hz
	100 KHz	—	—	–120	dBc/Hz
	≥ 1 MHz	—	—	–130	dBc/Hz
R _{REF}	—	—	2000 ±1%	—	Ω

Table 1-27: Transceiver Clocks Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	MHz
Transceiver Reconfiguration Controller IP (mgmt_clk_clk) clock frequency	—	75	—	125	MHz

Table 1-28: Receiver Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Supported I/O Standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS				
Data rate (6-Gbps transceiver) ⁽⁴⁴⁾	—	611	—	6553.6	Mbps

⁽⁴³⁾ The transmitter REFCLK phase jitter is 30 ps p-p (5 ps RMS) with bit error rate (BER) 10^{–12}, equivalent to 14 sigma.⁽⁴⁴⁾ To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{\text{OUTPJ_DC}}^{(67)}$	Period jitter for dedicated clock output in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	175	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	17.5	mUI (p-p)
$t_{\text{FOUTPJ_DC}}^{(67)}$	Period jitter for dedicated clock output in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	250 ⁽⁶⁸⁾ , 175 ⁽⁶⁹⁾	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	25 ⁽⁶⁸⁾ , 17.5 ⁽⁶⁹⁾	mUI (p-p)
$t_{\text{OUTCCJ_DC}}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	175	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	17.5	mUI (p-p)
$t_{\text{FOUTCCJ_DC}}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	250 ⁽⁶⁸⁾ , 175 ⁽⁶⁹⁾	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	25 ⁽⁶⁸⁾ , 17.5 ⁽⁶⁹⁾	mUI (p-p)
$t_{\text{OUTPJ_IO}}^{(67)(70)}$	Period jitter for clock output on a regular I/O in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ_IO}}^{(67)(68)(70)}$	Period jitter for clock output on a regular I/O in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ_IO}}^{(67)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{FOUTCCJ_IO}}^{(67)(68)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)

⁽⁶⁷⁾ Peak-to-peak jitter with a probability level of 10^{-12} (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

⁽⁶⁸⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be $\geq 1000 \text{ MHz}$.

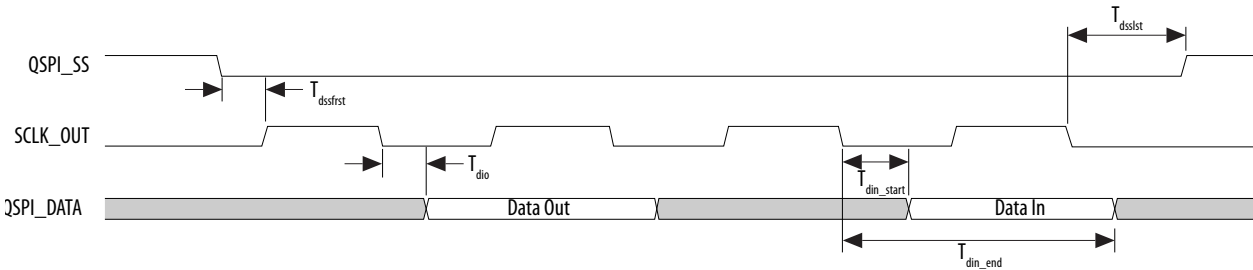
⁽⁶⁹⁾ This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.20–0.80 must be $\geq 1200 \text{ MHz}$.

⁽⁷⁰⁾ External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.

Symbol	Description	Min	Typ	Max	Unit
T_{din_end}	Input data valid end	$(2 + R_{delay}) \times T_{qspi_clk} - 1.21^{(85)}$	—	—	ns

Figure 1-8: Quad SPI Flash Timing Diagram

This timing diagram illustrates clock polarity mode 0 and clock phase mode 0.



Related Information

[Quad SPI Flash Controller Chapter, Arria V Hard Processor System Technical Reference Manual](#)

Provides more information about Rdelay.

SPI Timing Characteristics

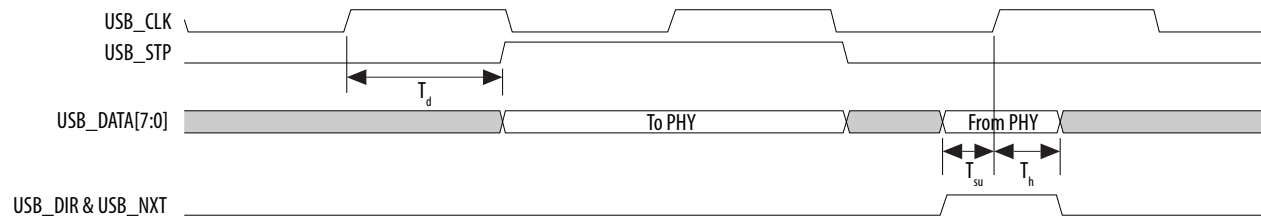
Table 1-52: SPI Master Timing Requirements for Arria V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

Symbol	Description	Min	Max	Unit
T_{clk}	CLK clock period	16.67	—	ns
T_{su}	SPI Master-in slave-out (MISO) setup time	8.35 ⁽⁸⁶⁾	—	ns

⁽⁸⁵⁾ R_{delay} is set by programming the register `qspiregs.rddatacap`. For the SoC EDS software version 13.1 and later, Altera provides automatic Quad SPI calibration in the preloader. For more information about R_{delay} , refer to the Quad SPI Flash Controller chapter in the Arria V Hard Processor System Technical Reference Manual.

Figure 1-12: USB Timing Diagram



Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
T_{clk} (1000Base-T)	TX_CLK clock period	—	8	—	ns
T_{clk} (100Base-T)	TX_CLK clock period	—	40	—	ns
T_{clk} (10Base-T)	TX_CLK clock period	—	400	—	ns
$T_{duty cycle}$	TX_CLK duty cycle	45	—	55	%
T_d	TX_CLK to TXD/TX_CTL output data delay	-0.85	—	0.15	ns

Figure 1-13: RGMII TX Timing Diagram

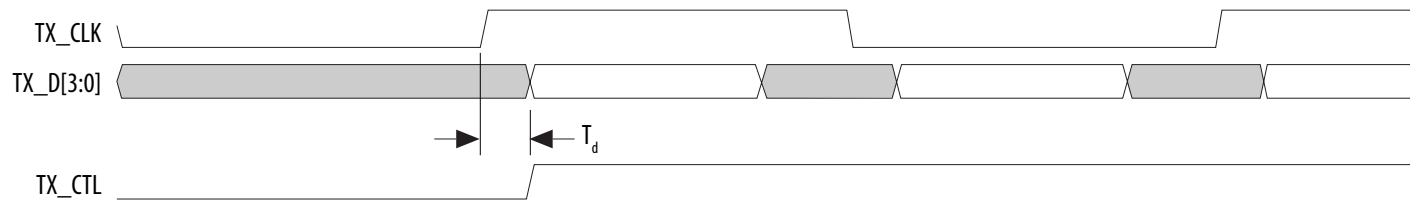
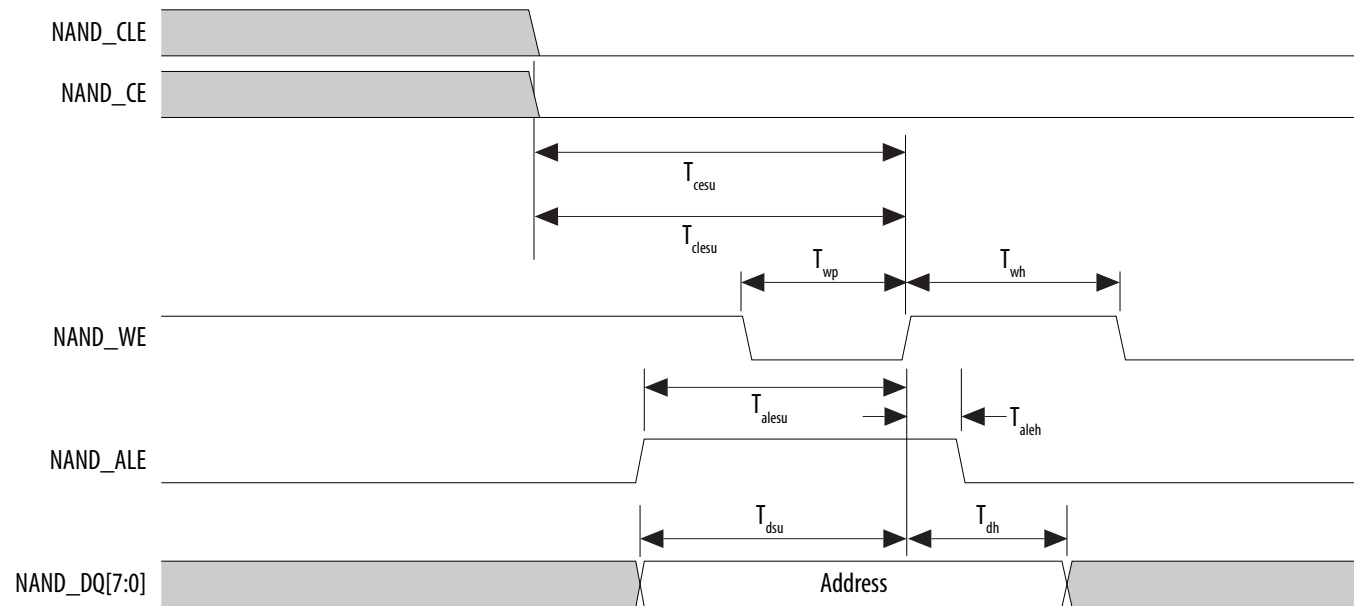
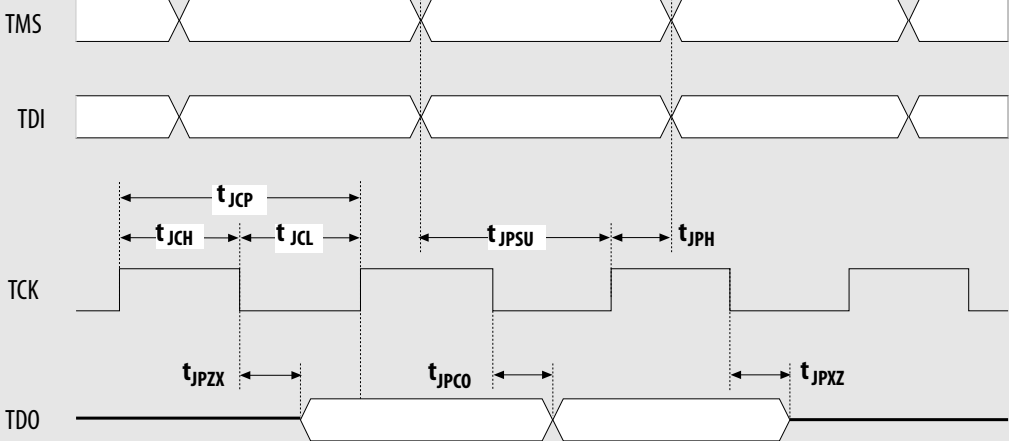


Figure 1-18: NAND Address Latch Timing Diagram



Variant	Member Code	Active Serial ⁽¹⁰⁸⁾			Fast Passive Parallel ⁽¹⁰⁹⁾		
		Width	DCLK (MHz)	Minimum Configuration Time (ms)	Width	DCLK (MHz)	Minimum Configuration Time (ms)
Arria V GX	A1	4	100	178	16	125	36
	A3	4	100	178	16	125	36
	A5	4	100	255	16	125	51
	A7	4	100	255	16	125	51
	B1	4	100	344	16	125	69
	B3	4	100	344	16	125	69
	B5	4	100	465	16	125	93
	B7	4	100	465	16	125	93
Arria V GT	C3	4	100	178	16	125	36
	C7	4	100	255	16	125	51
	D3	4	100	344	16	125	69
	D7	4	100	465	16	125	93
Arria V SX	B3	4	100	465	16	125	93
	B5	4	100	465	16	125	93
Arria V ST	D3	4	100	465	16	125	93
	D5	4	100	465	16	125	93

Related Information**Configuration Files** on page 1-83⁽¹⁰⁸⁾ DCLK frequency of 100 MHz using external CLKUSR.⁽¹⁰⁹⁾ Maximum FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Term	Definition
JTAG timing specifications	JTAG Timing Specifications  The diagram illustrates the timing relationships between JTAG signals TMS, TDI, TCK, and TDO. TMS and TDI are high during the first two clock cycles and low during the next two. TCK is a periodic clock signal. TDO is high during the first two clock cycles and low during the next two. Various timing parameters are indicated: t_{JCP} (TMS to TDI setup), t_{JCH} (TCK to TMS setup), t_{JCL} (TCK to TMS hold), t_{JPSU} (TCK to TDO setup), t_{JPH} (TCK to TDO hold), t_{JPZX} (TCK to TDO setup), t_{JPCO} (TCK to TDO hold), and t_{JPXZ} (TCK to TDO hold).

Related Information

- [PowerPlay Early Power Estimator User Guide](#)
For more information about the EPE tool.
- [PowerPlay Power Analysis](#)
For more information about PowerPlay power analysis.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus II PowerPlay Power Analyzer feature.

Note: You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- [PowerPlay Early Power Estimator User Guide](#)
For more information about the EPE tool.
- [PowerPlay Power Analysis](#)
For more information about PowerPlay power analysis.

I/O Pin Leakage Current**Table 2-8: I/O Pin Leakage Current for Arria V GZ Devices**

If $V_O = V_{CCIO}$ to $V_{CCIO_{MAX}}$, 100 μA of leakage current per I/O is expected.

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0\text{ V to }V_{CCIO_{MAX}}$	-30	—	30	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIO_{MAX}}$	-30	—	30	μA

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{ol} (mA)$	$I_{oh} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
SSTL-135 Class I, II	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-125 Class I, II	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
SSTL-12 Class I, II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 * V_{CCIO}$	$0.8 * V_{CCIO}$	—	—
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	—	—

I/O Standard	V _{CCIO} (V)			V _{DIF(DC)} (V)		V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	—	0.5 × V _{CCIO}	—	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5 × V _{CCIO} - 0.12	0.5 × V _{CCIO}	0.5 × V _{CCIO} + 0.12	0.4 × V _{CCIO}	0.5 × V _{CCIO}	0.6 × V _{CCIO}	0.44	0.44

Table 2-21: Differential I/O Standard Specifications for Arria V GZ Devices

I/O Standard	V _{CCIO} (V) ⁽¹²⁸⁾			V _{ID} (mV) ⁽¹²⁹⁾			V _{ICM(DC)} (V)			V _{OD} (V) ⁽¹³⁰⁾			V _{OCM} (V) ⁽¹³⁰⁾		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to the "Transceiver Performance Specifications" section.														
2.5 V LVDS ⁽¹³¹⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	—	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	—	0.6	1.125	1.25	1.375
						—	1.05	D _{MAX} > 700 Mbps	1.55	0.247	—	0.6	1.125	1.25	1.375
BLVDS ⁽¹³²⁾	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—

⁽¹²⁸⁾ Differential inputs are powered by VCCPD which requires 2.5 V.

⁽¹²⁹⁾ The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.

⁽¹³⁰⁾ RL range: 90 ≤ RL ≤ 110 Ω.

⁽¹³¹⁾ For optimized LVDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.

⁽¹³²⁾ There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

Typical VOD Settings

Table 2-32: Typical V_{OD} Setting for Arria V GZ Channel, TX Termination = 100 Ω

The tolerance is +/-20% for all VOD settings except for settings 2 and below.

Symbol	V_{OD} Setting	V_{OD} Value (mV)	V_{OD} Setting	V_{OD} Value (mV)
V_{OD} differential peak to peak typical	0 ⁽¹⁶⁶⁾	0	32	640
	1 ⁽¹⁶⁶⁾	20	33	660
	2 ⁽¹⁶⁶⁾	40	34	680
	3 ⁽¹⁶⁶⁾	60	35	700
	4 ⁽¹⁶⁶⁾	80	36	720
	5 ⁽¹⁶⁶⁾	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920

⁽¹⁶⁶⁾ If TX termination resistance = 100 Ω , this VOD setting is illegal.

Symbol	Parameter	Min	Typ	Max	Unit
k_{VALUE}	Numerator of Fraction	128	8388608	2147483648	—
f_{RES}	Resolution of VCO frequency ($f_{\text{INPFD}} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Related Information

- [Duty Cycle Distortion \(DCD\) Specifications](#) on page 2-56
- [DLL Range Specifications](#) on page 2-53

DSP Block Specifications**Table 2-35: DSP Block Performance Specifications for Arria V GZ Devices**

Mode	Performance			Unit
	C3, I3L	C4	I4	
Modes using One DSP Block				
Three 9×9	480	420		MHz
One 18×18	480	420	400	MHz
Two partial 18×18 (or 16×16)	480	420	400	MHz
One 27×27	400	350		MHz
One 36×18	400	350		MHz
One sum of two 18×18 (One sum of two 16×16)	400	350		MHz
One sum of square	400	350		MHz
One 18×18 plus $36(a \times b) + c$	400	350		MHz
Modes using Two DSP Blocks				
Three 18×18	400	350		MHz
One sum of four 18×18	380	300		MHz

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Memory	C3	C4	I3L	I4	
M20K Block	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	455	400	455	400	MHz
	Simple dual-port with ECC enabled, 512×32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512×32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Typ	Max	Unit
I_{bias} , diode source current	8	—	200	μA
V_{bias} , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{\text{HSDRDP A}}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.

(195) Requires package skew compensation with PCB trace length.

(196) Do not mix single-ended I/O buffer within LVDS I/O bank.

(197) Chip-to-chip communication only with a maximum load of 5 pF.

(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}) provided you can close the design timing and the signal integrity simulation is clean.

(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions ⁽²⁰¹⁾	Maximum
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Soft CDR Mode High-Speed I/O Specifications

Table 2-44: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

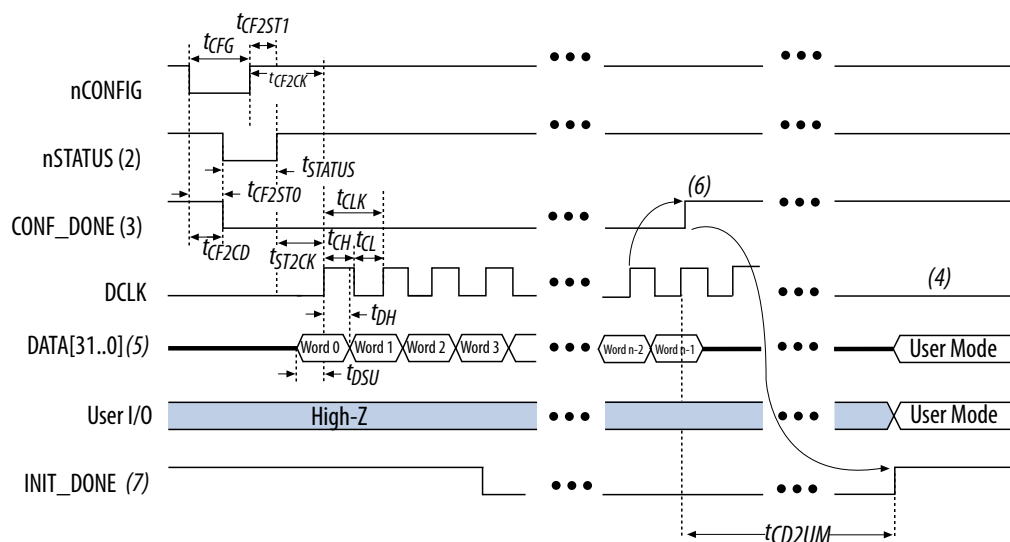
Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Soft-CDR ppm tolerance	—	—	—	300	—	—	300	± ppm

⁽²⁰¹⁾ This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

FPP Configuration Timing when DCLK to DATA[] = 1

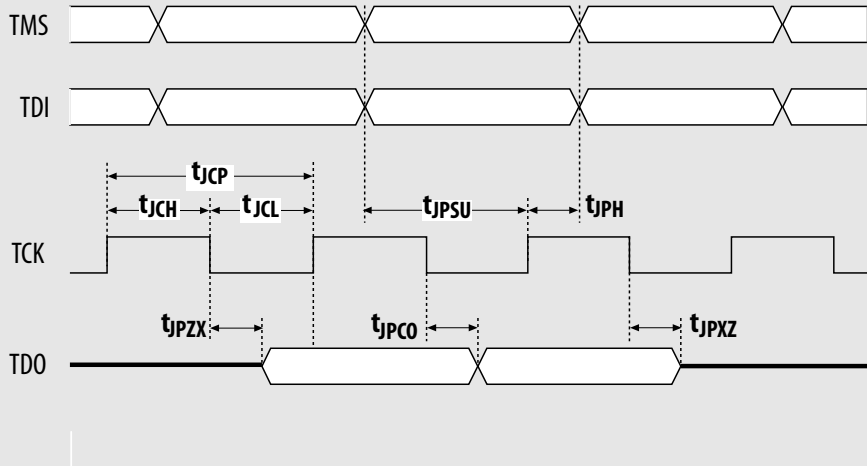
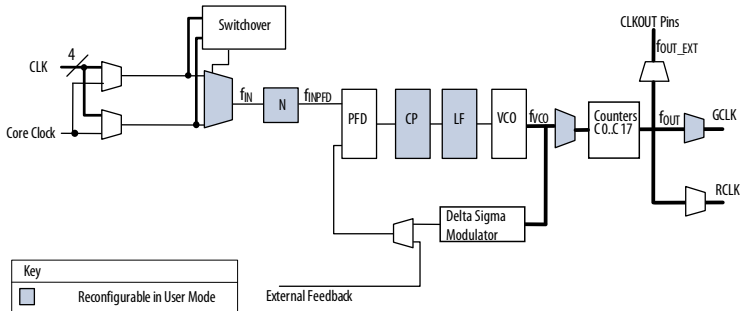
Figure 2-7: FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1

Timing waveform for FPP configuration when using a MAX[®] II or MAX V device as an external host.



Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. For FPP $\times 16$, use DATA[15..0]. For FPP $\times 8$, use DATA[7..0]. DATA[31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high when the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Term	Definition
JTAG Timing Specifications	JTAG Timing Specifications: 
PLL Specifications	Diagram of PLL Specifications  Key Reconfigurable in User Mode Note: 1. Core Clock can only be fed by dedicated clock input pins or PLL outputs.